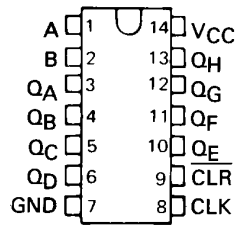
SN54164, SN54LS164, SN74164, SN74LS164
8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

MARCH 1974 – REVISED MARCH 1988

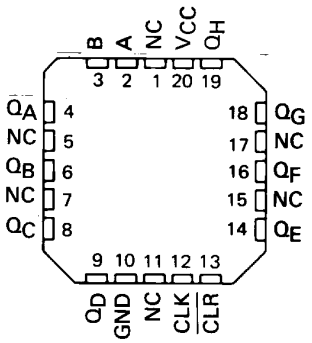
- **Gated Serial Inputs**
- **Fully Buffered Clock and Serial Inputs**
- **Asynchronous Clear**

TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY	TYPICAL POWER DISSIPATION
'164	36 MHz	21 mW per bit
'LS164	36 MHz	10 mW per bit

SN54164, SN54LS164 . . . J OR W PACKAGE
SN74164 . . . N PACKAGE
SN74LS164 . . . D OR N PACKAGE
(TOP VIEW)



SN54LS164 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

These 8-bit shift registers feature gated serial inputs and an asynchronous clear. The gated serial inputs (A and B) permit complete control over incoming data as a low at either input inhibits entry of the new data and resets the first flip-flop to the low level at the next clock pulse. A high-level input enables the other input which will then determine the state of the first flip-flop. Data at the serial inputs may be changed while the clock is high or low, but only information meeting the setup-time requirements will be entered. Clocking occurs on the low-to-high-level transition of the clock input. All inputs are diode-clamped to minimize transmission-line effects.

The SN54164 and SN54LS164 are characterized for operation over the full military temperature range of −55°C to 125°C. The SN74164 and SN74LS164 are characterized for operation from 0°C to 70°C.

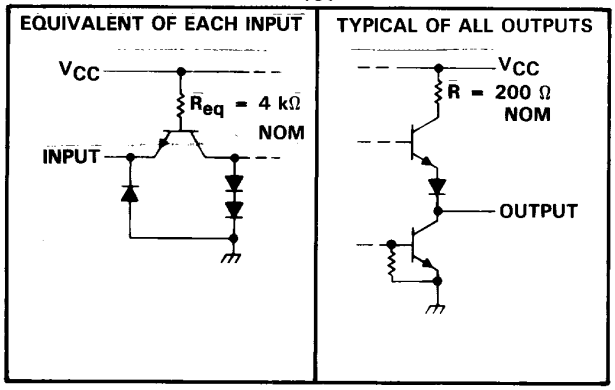
FUNCTION TABLE

INPUTS				OUTPUTS			
CLEAR	CLOCK	A	B	Q_A	Q_B	...	Q_H
L	X	X	X	L	L		L
H	L	X	X	Q_{A0}	Q_{B0}		Q_{H0}
H	↑	H	H	H	Q_{An}		Q_{Gn}
H	↑	L	X	L	Q_{An}		Q_{Gn}
H	↑	X	L	L	Q_{An}		Q_{Gn}

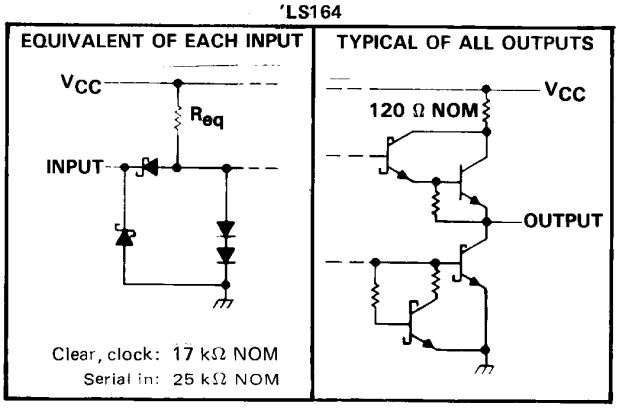
H = high level (steady state), L = low level (steady state)
X = irrelevant (any input, including transitions)
↑ = transition from low to high level.
Q_{A0}, Q_{B0}, Q_{H0} = the level of Q_A, Q_B, or Q_H, respectively, before the indicated steady-state input conditions were established.
Q_{An}, Q_{Gn} = the level of Q_A or Q_G before the most-recent ↑ transition of the clock; indicates a one-bit shift.

schematics of inputs and outputs

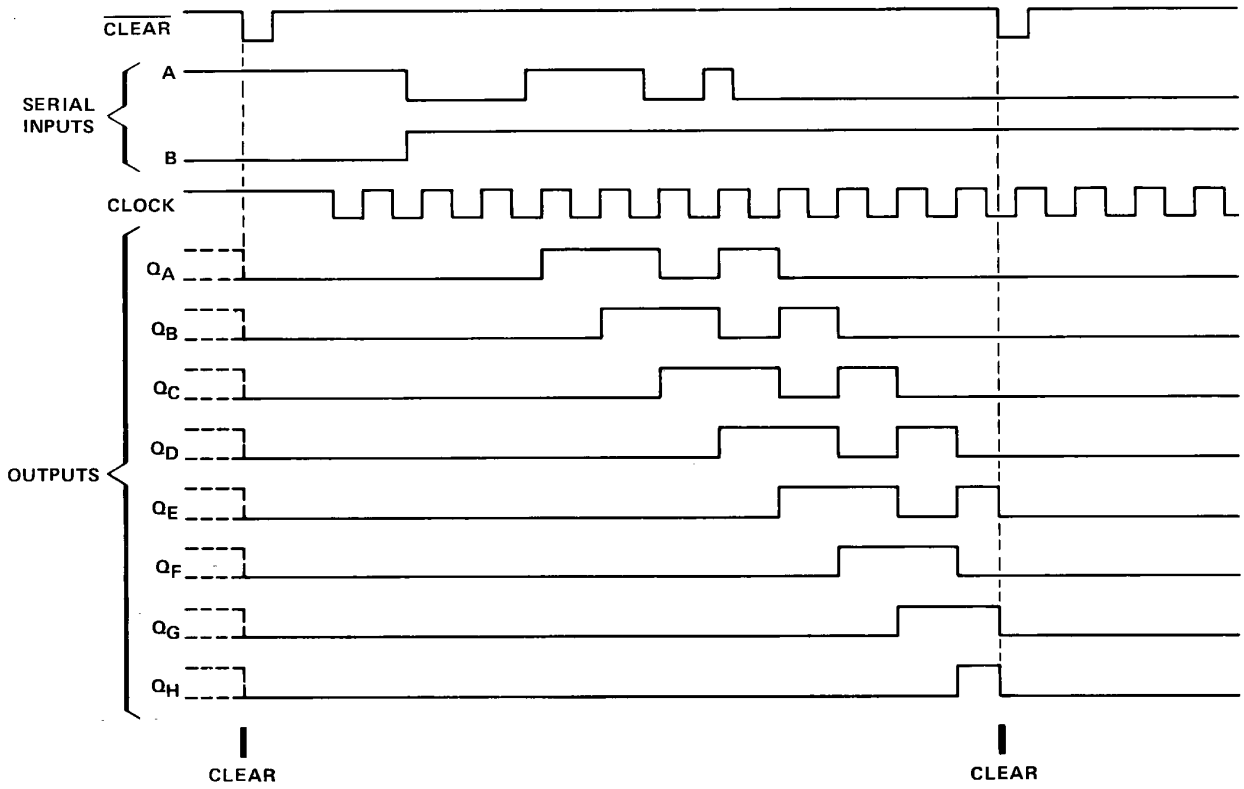
'164



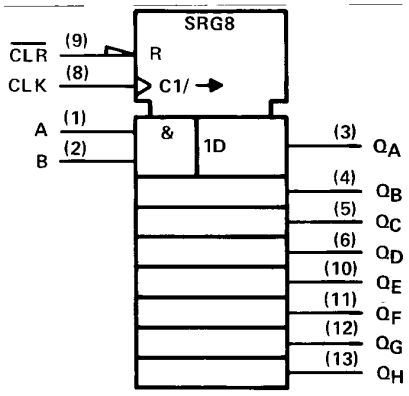
'LS164



typical clear, shift, and clear sequences

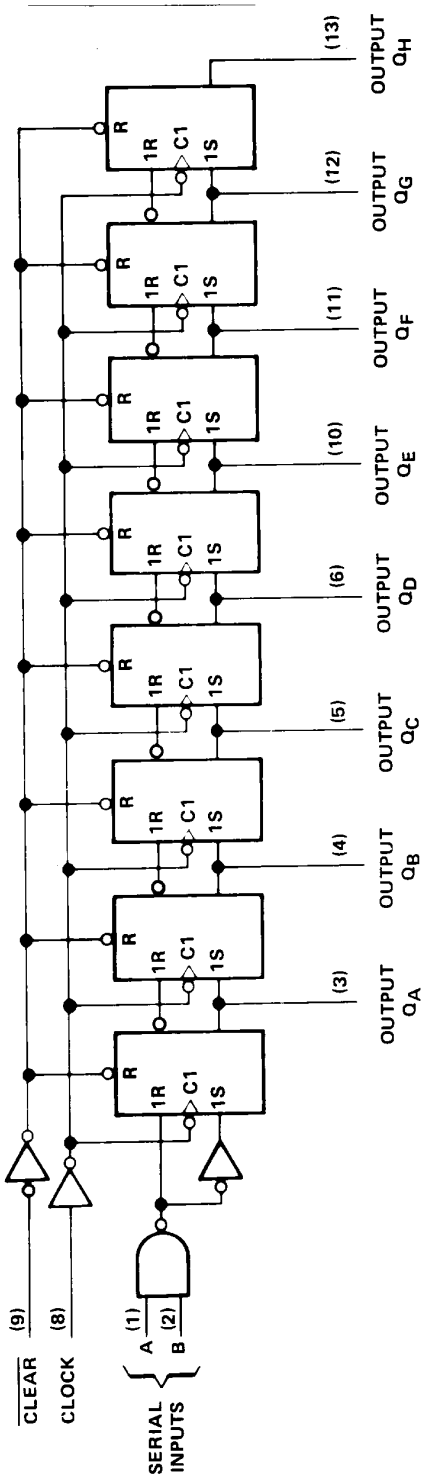


logic symbol†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

absolute maximum ratings over oprating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Operating free-air temperature range: SN54164 . . . . . −55°C to 125°C
SN74164 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54164			SN74164			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			−400			−400	μA
Low-level output current, I_{OL}			8			8	mA
Clock frequency, f_{clock}	0		25	0		25	MHz
Width of clock or clear input pulse, t_w	20			20			ns
Data setup time, t_{su} (see Figure 1)	15			15			ns
Data setup time, t_{su} (Clear Inactive) (see Figure 1)	20			20			ns
Data hold time, t_h (see Figure 1)	5			5			ns
Operating free-air temperature, T_A	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54164			SN74164			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage			2			2			V
V_{IL}	Low-level input voltage					0.8			0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN, I_I = −12 mA				−1.5			−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = −400 μA		2.4	3.2		2.4	3.2		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OL} = 8 mA			0.2	0.4		0.2	0.4	V
I_I	Input current at maximum input voltage	V_{CC} = MAX, V_I = 5.5 V,				1			1	mA
I_{IH}	High-level input current	V_{CC} = MAX, V_I = 2.4 V				40			40	μA
I_{IL}	Low-level input current	V_{CC} = MAX, V_I = 0.4 V				−1.6			−1.6	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX		−10		−27.5	−9		−27.5	mA
I_{CC}	Supply current	V_{CC} = MAX, See Note 2	$V_{I(clock)}$ = 0.4 V		30			30		mA
			$V_{I(clock)}$ = 2.4 V		37	54		37	54	

† For conditions shown at MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than two outputs should be shorted at a time.
NOTE 2: I_{CC} is measured with outputs open, serial inputs grounded, and a momentary ground, then 4.5 V, applied to clear.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
f_{max}	Maximum clock frequency	R_L = 800 Ω, See Figure 1	C_L = 15 pF	25	36		MHz
t_{PHL}	Propagation delay time, high-to-low-level Q outputs from clear input		C_L = 15 pF		24	36	ns
			C_L = 50 pF		28	42	
t_{PLH}	Propagation delay time, low-to-high-level Q outputs from clock input		C_L = 15 pF	8	17	27	ns
			C_L = 50 pF	10	20	30	
t_{PHL}	Propagation delay time, high-to-low-level Q outputs from the clock input		C_L = 15 pF	10	21	32	ns
			C_L = 50 pF	10	25	37	

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Operating free-air temperature range: SN54LS164 . . . . . −55°C to 125°C
SN74LS164 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS164			SN74LS164			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			−0.4			−0.4	mA
I_{OL}	Low-level output current			4			8	mA
f_{clock}	Clock frequency	0		25	0		25	MHz
t_w	Width of clock or clear input pulse	20			20			ns
t_{su}	Data setup time (See Figure 1)	15			15			ns
t_{su}	Clear inactive setup time (See Figure 1)	20			20			ns
t_h	Data hold time (See Figure 1)	5			5			ns
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

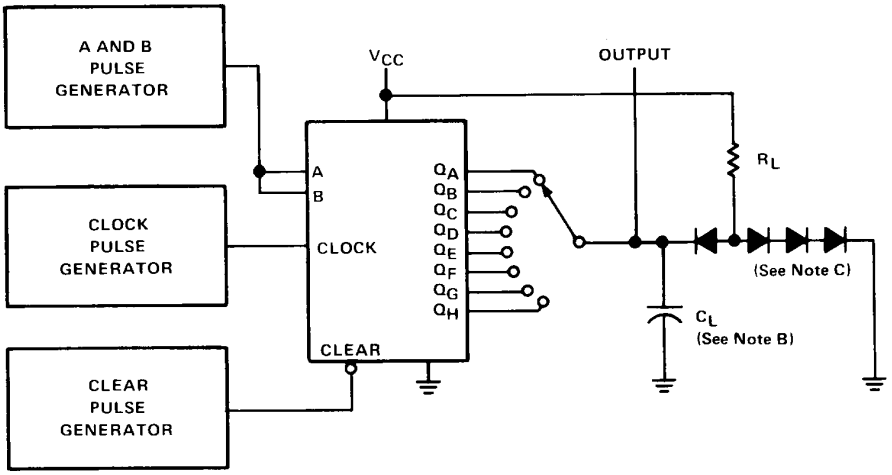
PARAMETER	TEST CONDITIONS†		SN54LS164			SN74LS164			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = −18 mA				−1.5			−1.5	V
V_{OH}	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX, I_{OH} = −0.4 mA		2.5	3.5		2.7	3.5		V
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
		I_{OL} = 8 mA					0.35	0.5	
I_I	V_{CC} = MAX, V_I = 7 V				0.1			0.1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.7 V			20			20		μA
I_{IL}	V_{CC} = MAX, V_I = 0.4 V				−0.4			−0.4	mA
I_{OS}	V_{CC} = MAX		−20		−100	−20		−100	mA
I_{CC}	V_{CC} = MAX, See Note 3			16	27		16	27	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.
NOTE 3: I_{CC} is measured with outputs open, serial inputs grounded, the clock input at 2.4 V, and a momentary ground, then 4.5 V applied to clear.

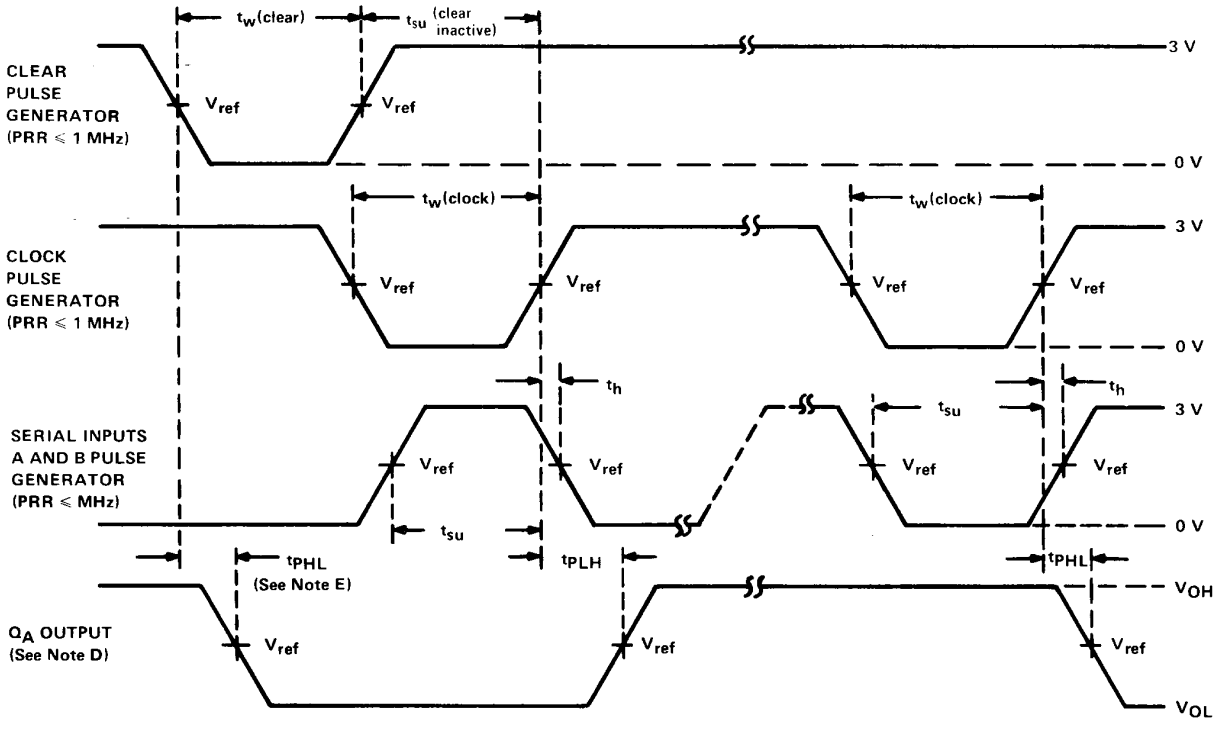
switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}	Maximum clock frequency	R_L = 2 kΩ, C_L = 15 pF, See Figure 1	25	36		MHz
t_{PHL}	Propagation delay time, high-to-low-level Q outputs from clear input			24	36	ns
t_{PLH}	Propagation delay time, low-to-high-level Q outputs from clock input			17	27	ns
t_{PHL}	Propagation delay time, high-to-low-level Q outputs from clock input			21	32	ns

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. The pulse generators have the following characteristics: duty cycle ≤ 50%, $Z_{out} \approx 50\ \Omega$; for '164, $t_r \leq 10$ ns, $t_f \leq 10$ ns; and for 'LS164, $t_r \leq 15$ ns, $t_f \leq 6$ ns.
B. C_L includes probe and jig capacitance.
C. All diodes are 1N3064 or equivalent.
D. Q_A output is illustrated. Relationship of serial input A and B data to other Q outputs is illustrated in the typical shift sequence.
E. Outputs are set to the high level prior to the measurement of t_{PHL} from the clear input.
F. For '164, V_{ref} = 1.5 V; for 'LS164, V_{ref} = 1.3 V.

FIGURE 1–SWITCHING TIMES

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
JM38510/30605B2A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30605B2A
JM38510/30605BCA	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30605BCA
JM38510/30605BCA	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30605BCA
JM38510/30605BDA	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30605BDA
JM38510/30605BDA	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30605BDA
JM38510/30605SCA	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30605SCA
JM38510/30605SCA	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30605SCA
JM38510/30605SDA	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30605SDA
JM38510/30605SDA	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 30605SDA
SN54LS164J	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS164J
SN54LS164J	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54LS164J
SN74LS164D	Obsolete	Production	SOIC (D) | 14	-	-	Call TI	Call TI	0 to 70	LS164
SN74LS164D	Obsolete	Production	SOIC (D) | 14	-	-	Call TI	Call TI	0 to 70	LS164
SN74LS164DR	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS164
SN74LS164DR	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS164
SN74LS164N	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS164N
SN74LS164N	Active	Production	PDIP (N) | 14	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74LS164N
SN74LS164NSR	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164
SN74LS164NSR	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164
SNJ54LS164FK	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS 164FK
SNJ54LS164FK	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS 164FK

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SNJ54LS164J	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS164J
SNJ54LS164J	Active	Production	CDIP (J) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS164J
SNJ54LS164W	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS164W
SNJ54LS164W	Active	Production	CFP (W) | 14	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SNJ54LS164W

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

OTHER QUALIFIED VERSIONS OF SN54LS164, SN54LS164-SP, SN74LS164 :

- Catalog : SN74LS164, SN54LS164

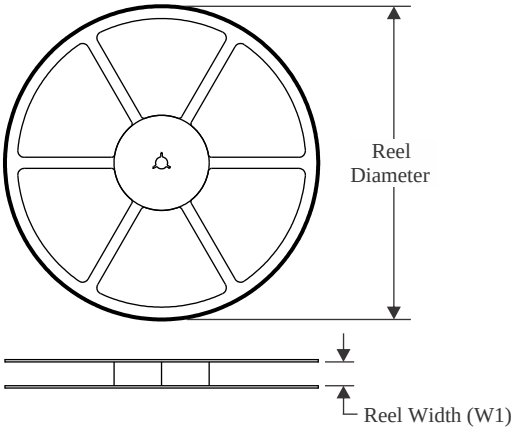
- Military : SN54LS164
- Space : SN54LS164-SP

NOTE: Qualified Version Definitions:

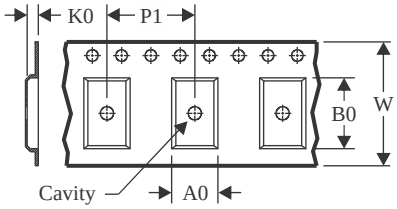
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

REEL DIMENSIONS

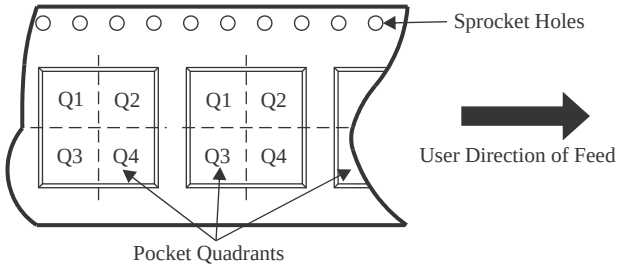


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

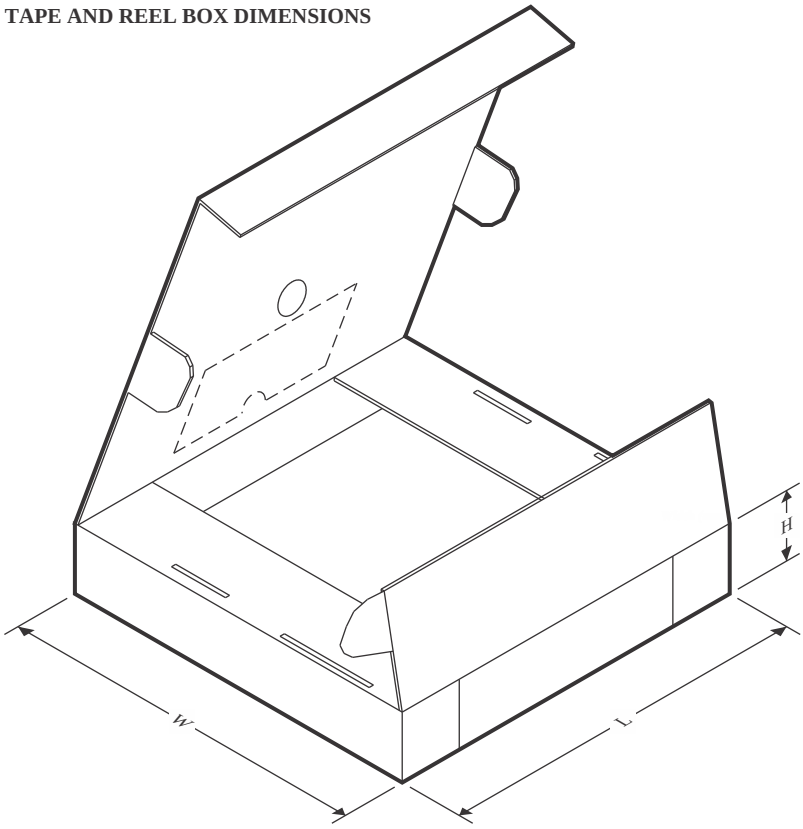
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS164DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS164DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS164NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

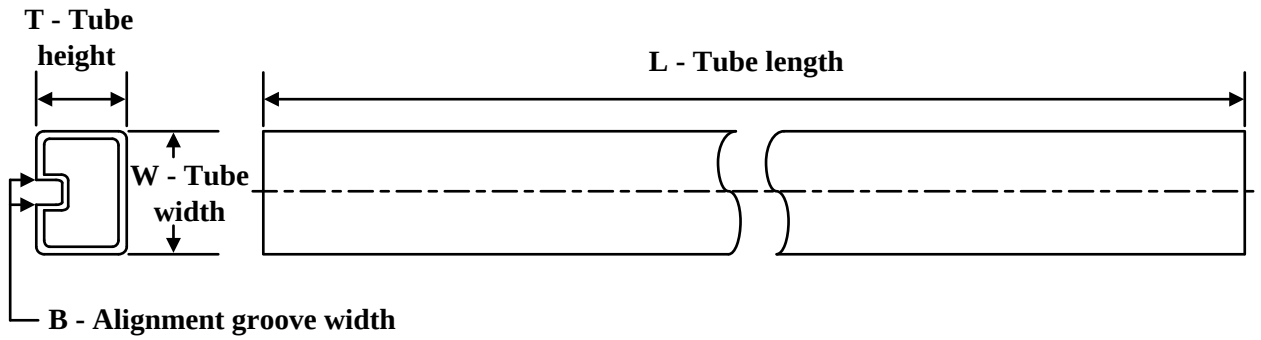
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

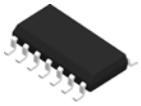
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS164DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LS164DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LS164NSR	SOP	NS	14	2000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/30605B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
JM38510/30605BDA	W	CFP	14	25	506.98	26.16	6220	NA
JM38510/30605SDA	W	CFP	14	25	506.98	26.16	6220	NA
M38510/30605B2A	FK	LCCC	20	55	506.98	12.06	2030	NA
M38510/30605BDA	W	CFP	14	25	506.98	26.16	6220	NA
M38510/30605SDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74LS164N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS164N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS164NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS164NE4	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS164FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54LS164W	W	CFP	14	25	506.98	26.16	6220	NA

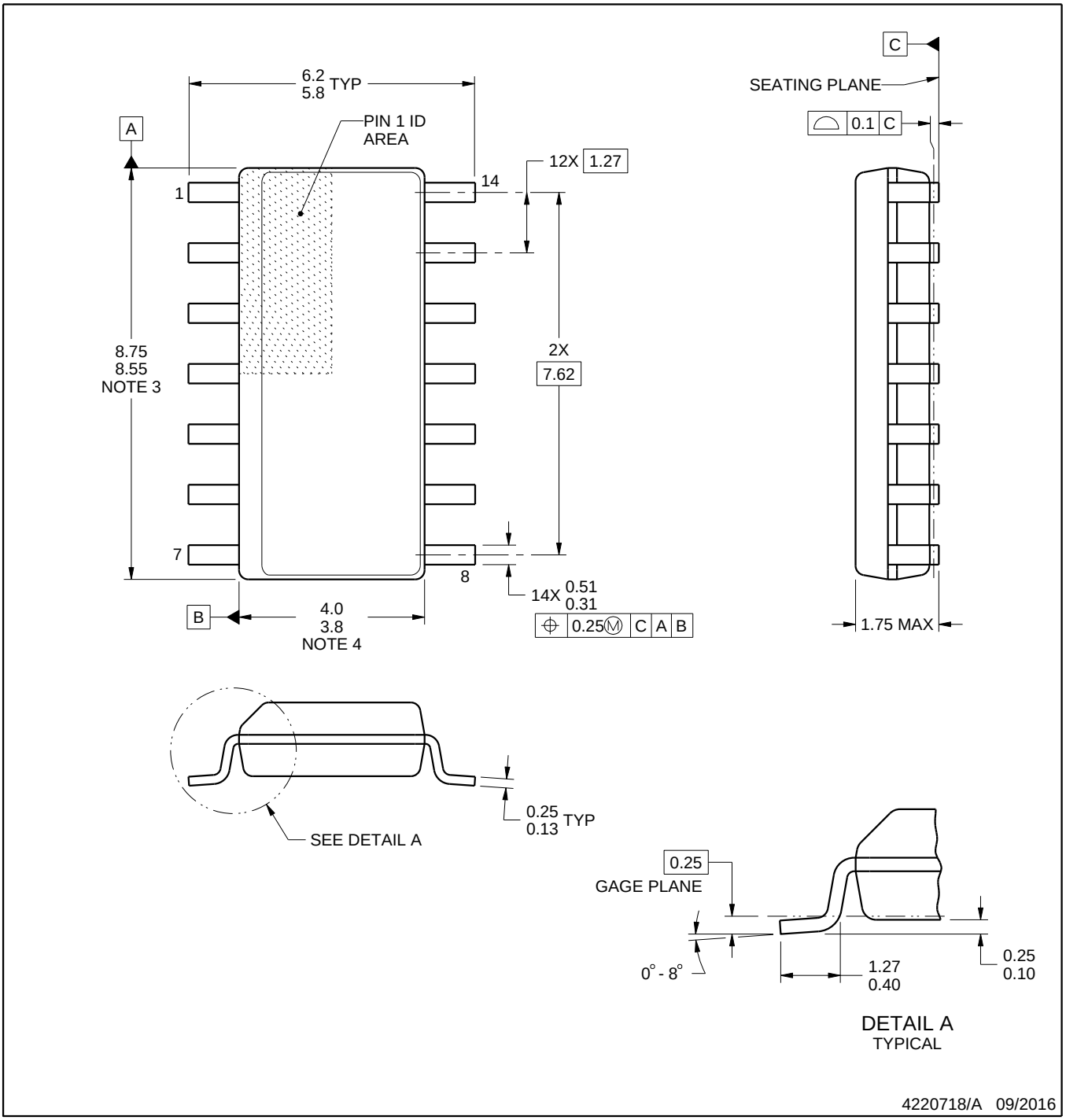


PACKAGE OUTLINE

D0014A

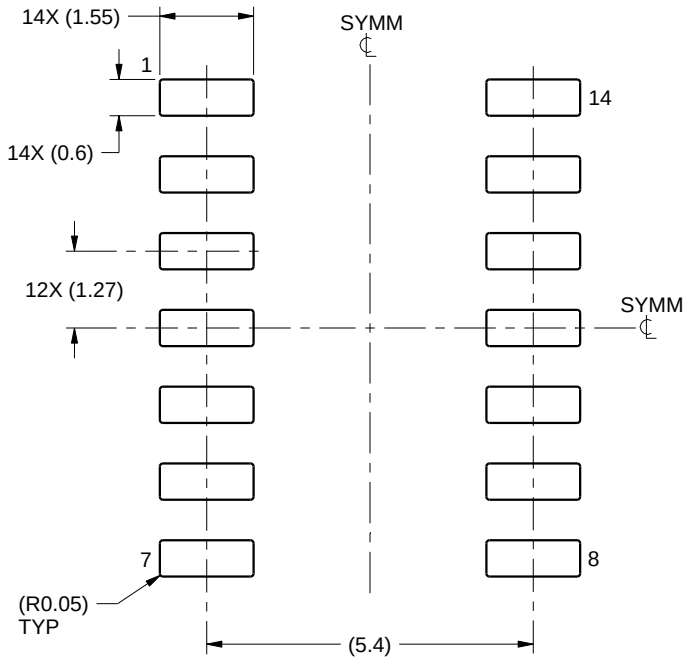
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

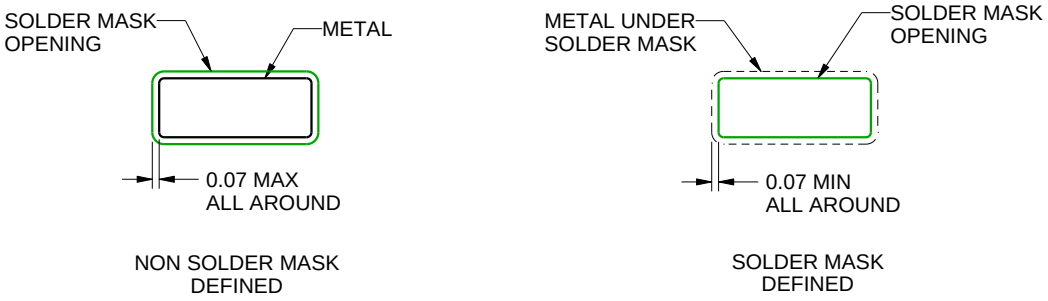


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

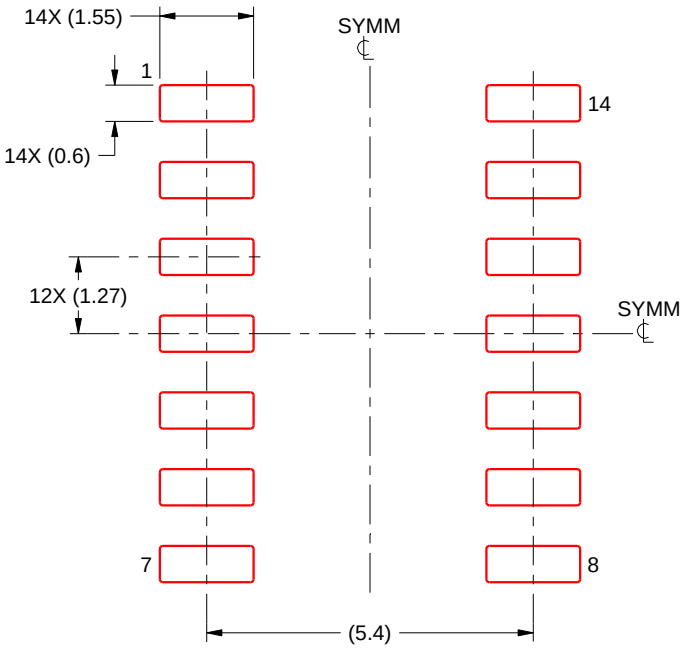
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

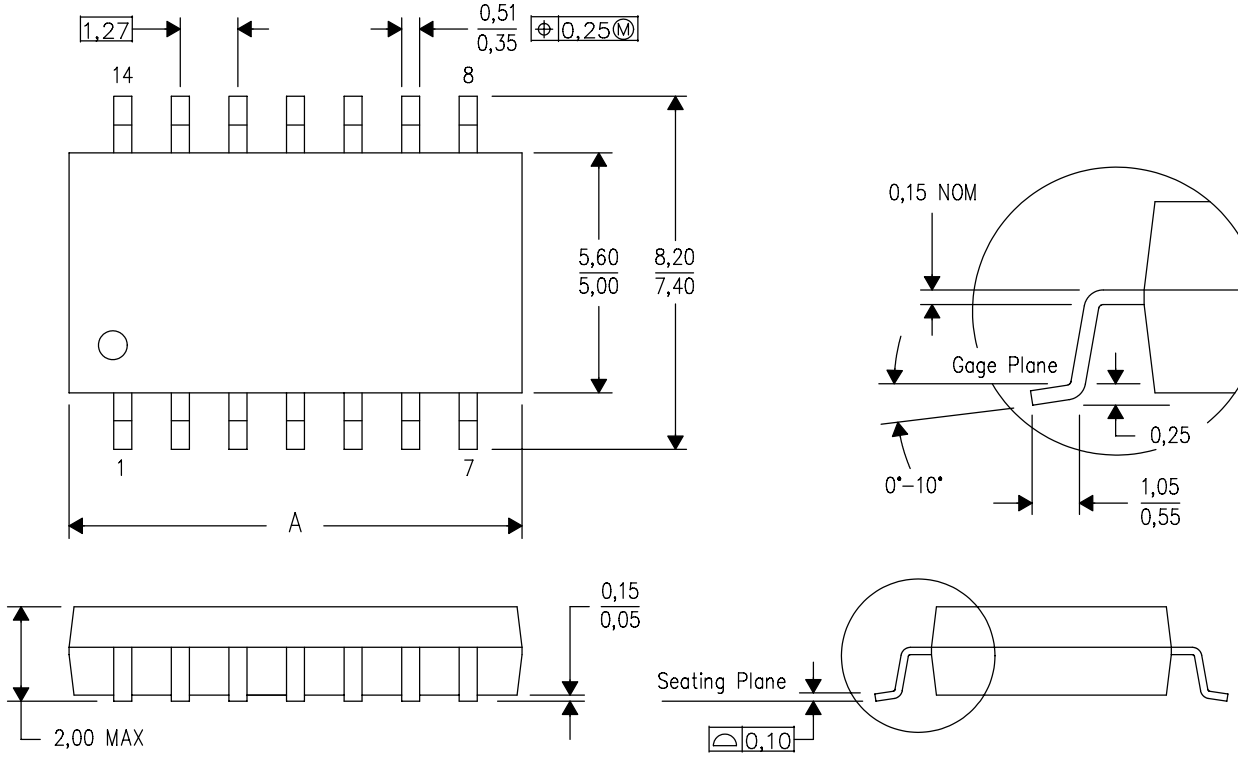
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN

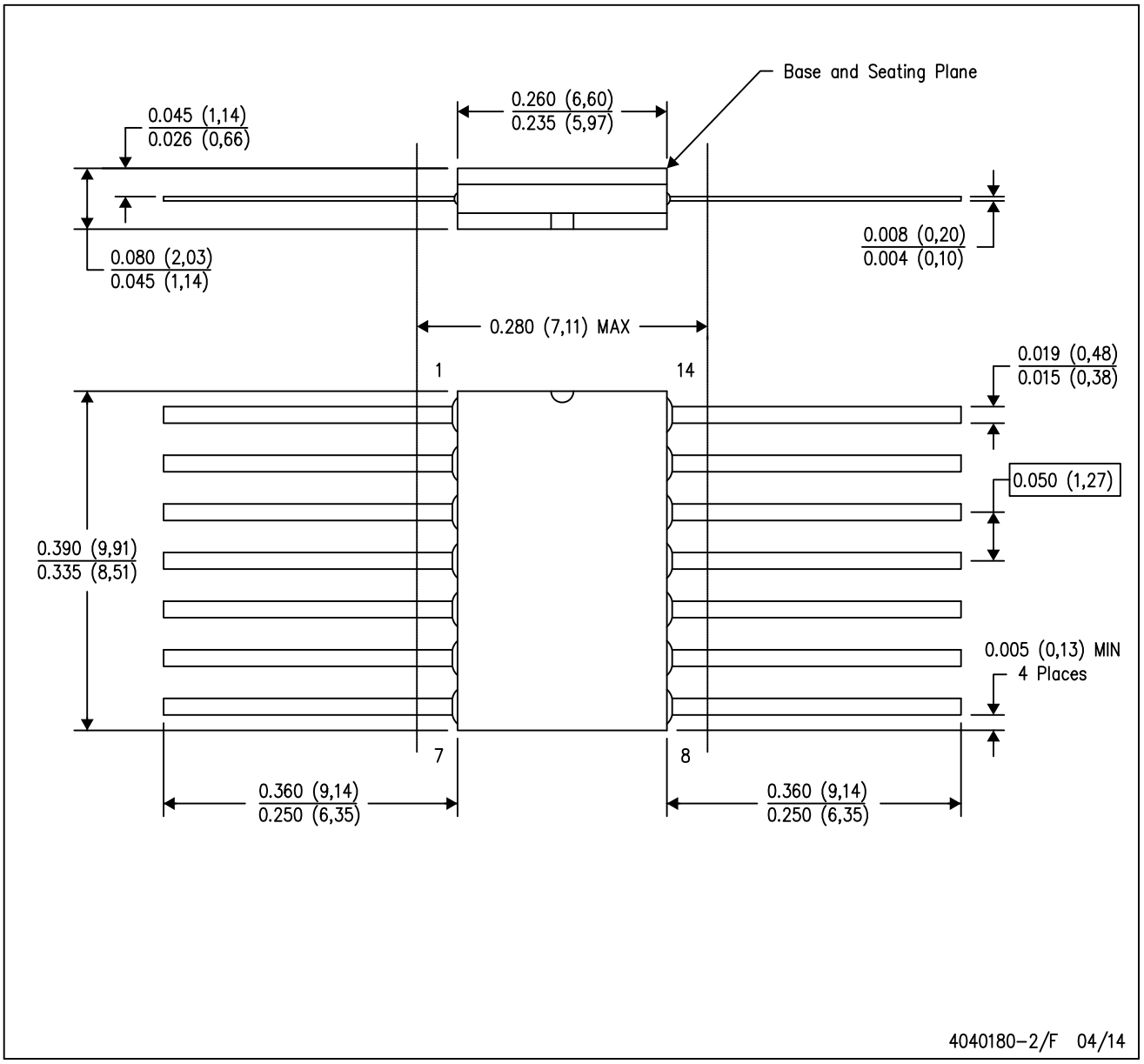


DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R–GDFP–F14) CERAMIC DUAL FLATPACK



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14

GENERIC PACKAGE VIEW

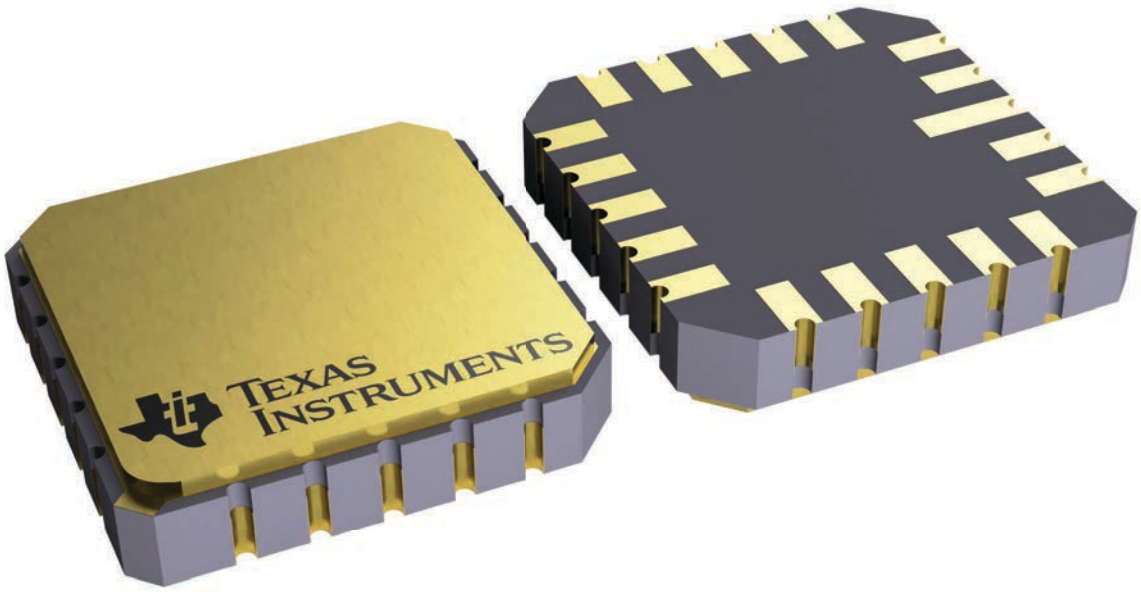
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

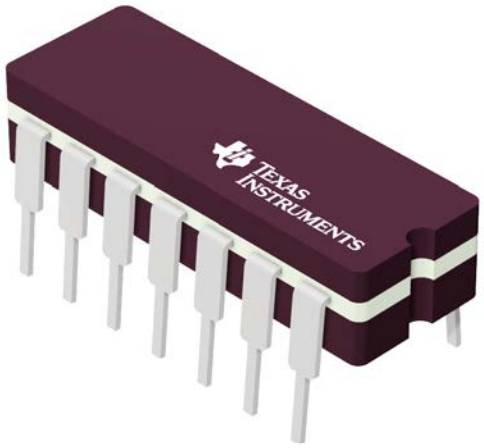


4229370VA\

GENERIC PACKAGE VIEW

J 14 CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

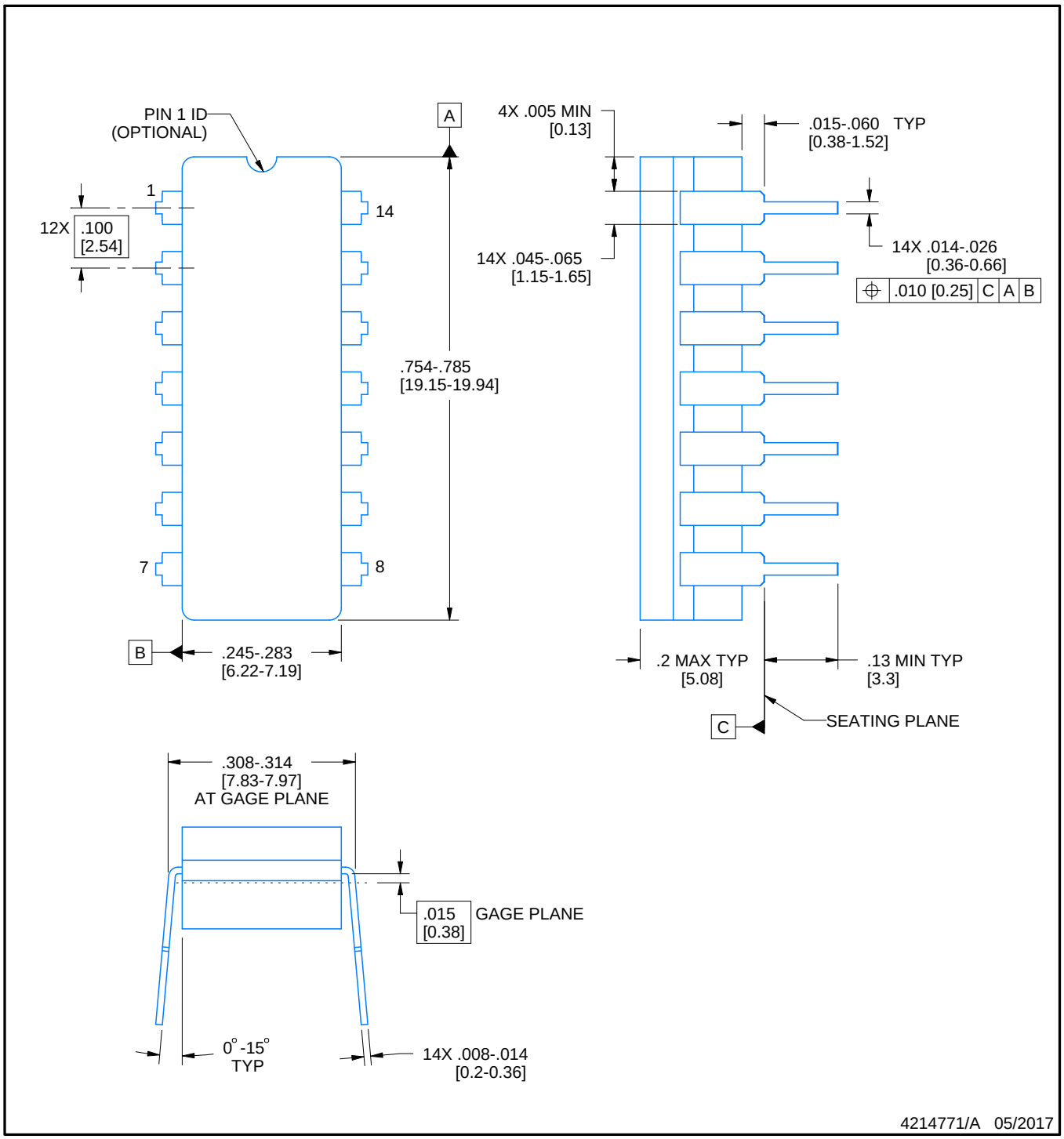
4040083-5/G

PACKAGE OUTLINE

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

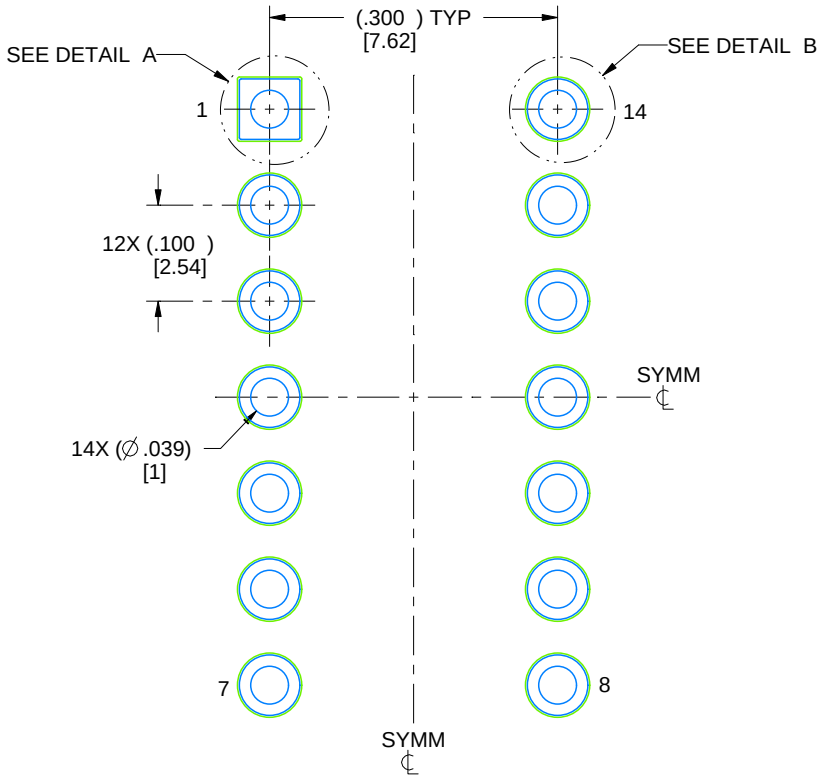
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

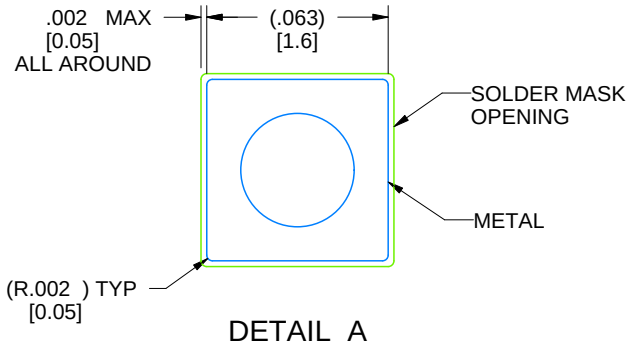
J0014A

CDIP - 5.08 mm max height

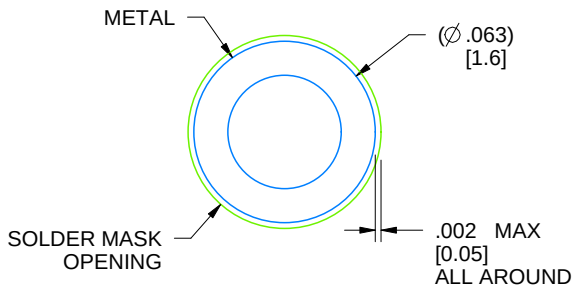
CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



DETAIL A
SCALE: 15X



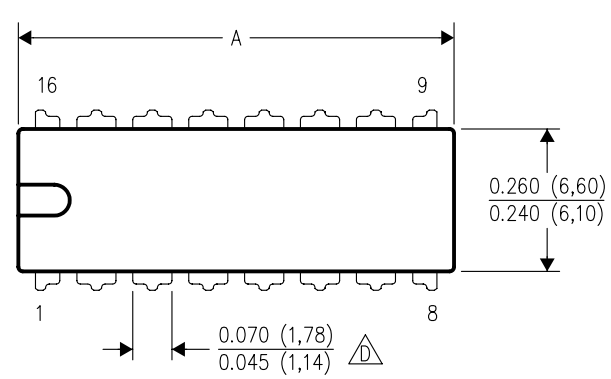
DETAIL B
13X, SCALE: 15X

4214771/A 05/2017

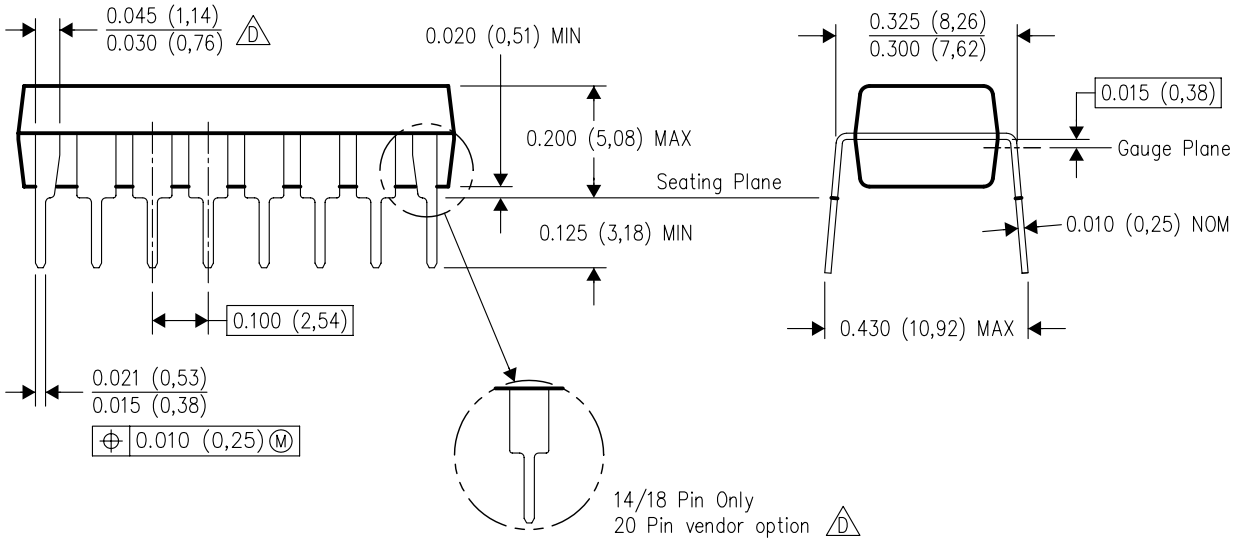
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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